12-17-2001

FORM PTO-1596

DOCKET NO.: 2336-086

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto: 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): Jeong-Goo YOON and Ju-Young PARK Name: SAMSUNG ELECTRO-MECHANICS CO., LTD. Internal Address: Additional name(s) of conveying party(ies) attached? 3. Nature of conveyance: X Assignment Merger Street Address: 314 Maetan-3-dong, Paldal-ku, Suwon Security Agreement Change of Name Other City: Kyungki-do State or Area: Zip/Postal Code: Country: Republic of Korea Execution Date: November 30, 2001 Additional name(s) & address(es) attached? 4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is: November 30, 2001 A. Patent Application No(s). B. Patent No(s). Additional numbers attached? 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: one concerning document should be mailed: Name: 7. Total fee (37 CFR 3.41) \$40.00 LOWE HAUPTMAN GILMAN & BERNER 🖾 Credit Card payment form enclosed \square Authorized to be charged to deposit account Internal Address: Street Address: 1700 Diagonal Road, Suite 310 8. Deposit account number: 07-1337 City: Alexandria State: VA ZIP: 22314 DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Benjamin / Hauptman Reg. No. December 10, 2001

CMB No. 085 10011

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PATENT

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Total number of pages comprising cover sheet: 3

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) _	YOON, Jeong-Goo (4)
(2) _	PARK, Ju-Young (5)
(3) _	(6)
who '	have made a certain new and useful invention, hereby sell, assign and
	fer unto
C A NA	SUNG ELECTRO-MECHANICS CO., LTD.
	Maetan-3-dong, Paldal-ku, Suwon,
Kyui	ngki-do, Republic of Korea
its sı	uccessors and assigns (hereinafter designated "ASSIGNEE") the entire
right	, title and interest for the United States of America as defined in 35 U.S.C.
100	in the invention entitled PROCESS FOR LAPPING WAFER AND
MET	HOD FOR PROCESSING BACKSIDE OF WAFER USING THE SAME
(a) f	or which an application for United States Letters Patent was filed on
	, and identified by United States Serial No;
or	
(b) f	or which an application for United States Letters Patent was executed on
	the undersigned hereby authorize and request the United States
Con	nmissioner of Patents and Trademarks to issue any and all United States
Lette	ers Patent which may be granted therefor and any and all extensions,
divis	sions, reissues, substitutes, renewals, continuations, or continuations-in-
part	thereof, and the right to all benefits under the International Convention for
the	Protection of Industrial Property to the said ASSIGNEE, for its interest as

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ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements. and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTOR(S)

DATE SIGNED

Name: PARK, Ju-Young

RECORDED: 12/10/2001

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